Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A method of forming a plurality of films on a base, the method comprising:

setting a plurality of relative positions of at least one nozzle to the base, the setting of the plurality of relative positions including moving at least one of the at least one nozzle and the base;

ejecting a first ~~gasified~~ material in a form of gas from the at least one nozzle toward the base at each of the plurality of relative positions; and

detecting an ejection failure of the at least one ~~nozzle.~~nozzle,

each of the plurality of films including the first material.

2. (Currently Amended) The method according to Claim 1,

the base being provided in a vacuum atmosphere that is adjusted to a pressure of 10^{-3} torr or less during at least a period in which the ejecting of the first ~~gasified~~ material in the form of gas is carried out.

3. (Currently Amended) The method according to Claim 1,

the base being provided in a vacuum atmosphere that is adjusted to a pressure of 10^{-5} torr or less during at least a period in which the ejecting of the first ~~gasified~~ material in the form of gas is carried out.

4. (Currently Amended) The method according to Claim 1, the detecting of the ejection failure of the at least one nozzle including a preliminary ejection of the first ~~gasified~~ material in the form of gas to a preliminary-ejecting area provided in a preliminary member provided in a predetermined area on the base, and

the plurality of films being to be formed in the predetermined area.

5. (Currently Amended) The method according to Claim 1, the detecting of the ejection failure of the at least one nozzle including a preliminary ejection of the first ~~gasified~~ material in the form of gas to a preliminary-ejecting area provided in a preliminary member in a predetermined area on the base, and

the ejection failure being detected on the basis of an inspection of a preliminary film that is formed on the preliminary-ejecting area by the preliminary ejection.

6. (Previously Presented) The method according to Claim 5, the inspection of the preliminary film being performed by a measurement of light-reflectivity of the preliminary film.

7. (Previously Presented) The method according to Claim 5, the inspection of the preliminary film being performed by a measurement of light-transmissivity of the preliminary film.

8. (Currently Amended) The method according to Claim 1, further comprising ejecting a second ~~gasified~~ material in a form of gas from the at least one nozzle,

the detecting ~~an~~ of the ejection failure of the at least one nozzle being carried out prior to the ejecting of the second ~~gasified~~ material in the form of gas from the at least one nozzle.

9. (Currently Amended) A method of forming of plurality of films, the method comprising:

setting a first relative position of at least one nozzle to the base, the setting of the first relative position including moving at least one of the at least one nozzle and the base;

ejecting a first ~~gasified~~ material in a form of gas to a first area of the base from at least one nozzle at the relative position, the plurality of films being to be formed in the first area; and

setting a second relative position of the at least one nozzle to the base, the setting of the second relative position including moving at least one of the at least one nozzle and the base; and

ejecting the first ~~gasified~~ material in the form of gas to a second area of the base other than the first area from the at least one nozzle at the second position,

the ejecting of the first ~~gasified~~ material in the form of gas to the second area being carried out prior to the ejecting of the first ~~gasified~~ material in the form of gas to the first ~~area.~~area, and each of the plurality of films including the first material.

10. (Currently Amended) The method according to Claim 9,

the base being provided in a vacuum atmosphere during at least a period in which the ejecting of the first ~~gasified~~ material in the form of gas to the first area is carried out.

11. (Currently Amended) The method according to Claim 9,

the base being provided in a vacuum atmosphere that is adjusted to 10^{-3} torr or less during at least a period in which the ejecting of the first ~~gasified~~ material in the form of gas to the first area is carried out.

12. (Canceled)

13. (Currently Amended) The method according to Claim 9, further comprising:

ejecting a second ~~gasified~~ material in a form of gas to the first area of the base from the at least one nozzle; and

ejecting the second ~~gasified~~ material in the form of gas to the second area,

the ejecting of the second ~~gasified~~ material in the form of gas to the second area being carried out prior to the ejecting of the second ~~gasified material.~~material in the form of gas to the first area.

14. (Currently Amended) The method according to Claim 9,

a positional deviation between a first position where a preliminary film is to be formed by ejecting of the first ~~gasified~~ material in the form of gas to the second area and a second position where the preliminary film is actually formed in the second area by the ejecting the first ~~gasified~~ material in the form of gas to the second area being detected, and

a positional correction of the at least one nozzle being carried out when the positional deviation is observed.

15. (Previously Presented) A method of manufacturing an electronic device, at least one element of elements constituting the electronic device being formed using the method according to Claim 1.

16. (Currently Amended) The method according to Claim 15, the first ~~gasified~~ material in the form of gas being for at least one layer of a conductive layer, a semiconductor layer, and an insulating layer of the at least one element.

17. (Currently Amended) The method according to Claim 15, further comprising providing a pattern prior to the ejecting of the first ~~gasified material,~~material in the form of gas,

the plurality of films being formed according to the ~~pattern by the first gasified material.~~pattern.

18. (Previously Presented) A method of manufacturing an electro-optical device, including a plurality of electro-optical elements, the plurality of electro-optical elements being formed using the method according to Claim 1.

19. (Currently Amended) The method according to Claim 18,

the plurality of electro-optical elements being a plurality of organic electroluminescent elements each of which includes an electron-transporting layer, a hole-transporting layer, a light-emitting layer, and electrodes, and

the first ~~gasified~~ material being used for at least one of the electron-transporting layer, the hole-transporting layer, the light-emitting layer, and the electrodes.

20. (Currently Amended) The method according to Claim 19, further comprising forming partitions that separate pixels from each other which are to be formed after the forming of the partitions and each of which corresponds to one of the plurality of electro-optical elements,

at least one of the light-emitting ~~layer among~~ layer, the electron-transporting layer, ~~the~~ and the hole-transporting ~~layer, and the light-emitting~~ layer being ~~formed on are~~ surrounded by the partitions.

21. (Withdrawn) A film-forming apparatus comprising:

a processing chamber;

a pressure control system that controls a pressure in the processing chamber to a low pressure;

at least one nozzle provided in the processing chamber and connected to a material supply source, that arrange a material on a member provided in the processing chamber;

a stage provided in the processing chamber that holds a member;

a moving device that relatively move a position of the nozzle or the stage; and

an inspecting device that inspects the material arranged on the member.

22. (Withdrawn) A film-forming apparatus comprising:

a processing chamber;

a pressure control system that controls a pressure in the processing chamber to a low pressure;

a head having a plurality of nozzles provided in the processing chamber and connected to a material supply source, that arrange a material on a member provided in the processing chamber;

a stage provided in the processing chamber that holds the member;

a moving device that relatively moves a position of the nozzles or the stage; and

an inspecting device that inspects the material arranged on the member.

23. (Withdrawn) The film-forming apparatus according to Claim 21, the member being a base having a predetermined area in which a film of the material is formed.

24. (Withdrawn) The film-forming apparatus according to Claim 21, the member being a preliminary member having a preliminary-ejecting area.

25. (Withdrawn) The film-forming apparatus according to Claim 21, the nozzles further including a preliminary nozzle to be used in place of a nozzle having an ejection failure, when the ejection failure occurs in one of the nozzles.

26. (Withdrawn) The film-forming apparatus according to Claim 21, the inspecting device including a detecting device for detecting an ejection failure of the nozzles on the basis of an ejecting result of the material.

27. (Withdrawn) The film-forming apparatus according to Claim 21, the inspecting device further comprising a position correcting device that detects an arranged position of the material and a target position to arrange the material and performing a positional correction of the nozzles when a positional deviation occurs between the arranged position and the target position.

28. (Withdrawn) An electronic device manufactured using the film-forming apparatus according to Claim 21.

29. (Withdrawn) An electro-optical device manufactured using the film-forming apparatus according to Claim 21.

30. (Withdrawn) An electronic apparatus comprising the electro-optical device according to Claim 29 as a display device.

31. (Currently Amended) The method according to Claim 1,

the detecting ~~an~~ of the ejection failure of the at least one nozzle being carried out using a sensor.

32. (Currently Amended) A method of forming a plurality of films on a base, the method comprising:

setting a plurality of relative positions of at least one nozzle to the base, the setting of the plurality of relative positions including moving at least one of the at least one nozzle and the base;

ejecting a first ~~gasified~~ material in a form of gas from the at least one nozzle toward the base at each of the plurality of relative positions; and

sensing at least one film of the plurality of films by a sensor.

33. (Currently Amended) The method according to Claim 32,

the sensing of the at least one film including an irradiation of the at least one film with a light source.

34. (Previously Presented) The method according to Claim 32,

the sensor measuring at least one of a transmission light that transmits the at least one film and a reflection light that is reflected by the at least one film.

35. (Currently Amended) The method according to Claim 32,

the base being provided in a vacuum atmosphere that is adjusted to 10^{-3} torr or less during at least a period in which the ejecting of the first ~~gasified~~ material in the form of gas is carried out.

36. (Currently Amended) A method of forming a plurality of films on a base, the method comprising:

ejecting a first ~~gasified~~ material in a form of gas from a nozzle of a plurality of nozzles and a second ~~gasified~~ material in a form of gas from a nozzle of the plurality of nozzles; and

sensing at least one film of the plurality of films by a sensor,

the plurality of nozzles moving during at least a part of a period in which the method is carried ~~out.~~out, and each of the plurality of films including the first material and the second material.

37. (Previously Presented) A method of manufacturing an electronic device, at least one element of elements constituting the electronic device being formed using the method according to Claim 32.

38. (Previously Presented) A method of manufacturing an electronic device, at least one element of elements constituting the electronic device being formed using the method according to Claim 36.

39. (Previously Presented) A method of manufacturing an electro-optical device including a plurality of electro-optical elements, the plurality of electro-optical elements being formed using the method according to Claim 36.

40. (Currently Amended) The method according to Claim 39,

the plurality of electro-optical elements being a plurality of organic electroluminescent elements each of which includes an electron-transporting layer, a hole-transporting layer, a light-emitting layer, and electrodes,

the first ~~gasified~~ material and the second ~~gasified~~ material being used for at least one of the electron-transporting layer, the hole-transporting layer, the light-emitting layer, and the electrodes, and

~~the~~ a formation of the light-emitting layer including a ~~co-evaporation~~ co-deposition process.

41. (Currently Amended) A method of manufacturing an electro-optical device including a plurality of electro-optical elements, the method comprising:

ejecting a first ~~gasified~~ material in a form of gas from a nozzle of a plurality of nozzles and a second ~~gasified~~ material in a form of gas from a nozzle of the plurality of nozzles,

the plurality of nozzles moving during at least a period in which the ejecting of the first ~~gasified~~ material in the form of gas and the second ~~gasified material,~~material in the form of gas,

~~the plurality of electro-optical elements being a plurality of organic electroluminescent elements each of which includes an electron-transporting layer, a hole-transporting layer, a light-emitting layer, and electrodes,~~

~~the first gasified material and the second gasified material being used for at least one of the electron-transporting layer, the hole-transporting layer, the light-emitting layer, and the electrodes, and~~

each of the plurality of electro-optical elements including a plurality of layers one of which includes at least one of the first material and the second material,

the plurality of layers including an electron-transporting layer, a hole-transporting layer, a light-emitting layer, and electrodes, and

~~the~~ a formation of the light-emitting layer including a ~~co-evaporation~~ co-deposition process.

42. (Currently Amended) A method of forming a plurality of films on a base, the method comprising:

ejecting a first ~~gasified~~ material in a form of gas from ~~the~~ at least one nozzle toward the base at each of a plurality of relative positions; and

sensing by a sensor at least one film of the plurality of ~~films by a sensor,~~films each of which includes the first material,

a scanning movement of the at least one nozzle being carried out during at least a part of a period in which the method is carried out.

43. (Currently Amended) A method of forming a plurality of films on a base, the method comprising:

ejecting a first ~~gasified~~ material in a form of gas from a nozzle of a plurality of nozzles and a second ~~gasified~~ material in a form of gas from a nozzle of the plurality of nozzles; and

sensing at least one film of the plurality of films by a sensor,

a scanning movement of the plurality of nozzles being carried out during at least a part of a period in which the method is carried out.

44. (Previously Presented) The method according to Claim 36,

the plurality of nozzles being provided in a discharge head.

45. (Currently Amended) The method according to Claim 44,

~~the discharge head moving along at least one of X-coordinate, Y-coordinate, and Z-coordinate during at least a part of a period in which the method is carried out.~~

the discharge head being constructed to adjust a posture of the discharge head by a θ direction adjusting mechanism, a Z direction adjusting mechanism, and a Y adjusting mechanism.

46. (Currently Amended) The method according to ~~Claim 44,~~Claim 45,

~~the discharge head rotating during at least a part of a period in which the method is carried out.~~

each of the θ direction adjusting mechanism, the Z direction adjusting mechanism, and the Y adjusting mechanism being operated.

47. (Currently Amended) The method according to Claim 1,

the base being provided in a vacuum atmosphere during at least a period in which the ejecting the first ~~gasified~~ material is carried out.

48. (Currently Amended) A method of forming a plurality of films on a base, the method comprising:

detecting an ejection failure of a first nozzle;

setting a first relative position of the first nozzle to the base, the setting of the relative position including moving at least one of the first nozzle and the base;

ejecting a first ~~gasified~~ material in a form of gas from the first nozzle toward the base at the first relative position;

detecting an ejection failure of a second nozzle;

setting a second relative position of the second nozzle to the base, the setting of the relative position including moving at least one of the second nozzle and the base; and

ejecting a second ~~gasified~~ material in a form of gas from the second nozzle toward the base at the second relative ~~position.~~position, and each of the plurality of films includes at least one of the first material and the second material.